IN THE CLAIMS

Please amend the claims as follows:

3. (Amended) A semiconductor chip package comprising:

a substrate having a plurality of bonding pads;

a semiconductor chip having a plurality of conductive bumps on a front side thereof, the conductive bumps contacting the bonding pads;

a heat slug bonded to a backside of the semiconductor chip; and

a solder film directly attached to the heat slug thereby bonding the heat slug to the backside of the semiconductor chip, wherein the backside of the semiconductor chip includes a solder bonding metal layer formed thereon for strengthening adhesion between the semiconductor chip and the solder film.

8. (Amended) The semiconductor chip package of claim 3, wherein the heat slug comprises a solder bonding layer formed on a surface of the heat slug that contacts the solder film.

9. (Amended) The semiconductor chip package of claim 8, wherein the solder bonding layer is a layer selected from a group consisting of a Ni/Au layer, a Ag layer, and a Pd layer.

14. (Amended) A method of fabricating a semiconductor chip package, comprising:

preparing the semiconductor chip having a plurality of conductive bumps on a front surface of the semiconductor chip and a solder bonding metal layer on a backside of the semiconductor chip;

bonding a heat slug on the backside of a semiconductor chip using a solder film; and

attaching the semiconductor chip on a substrate such that the conductive bumps of the semiconductor chip contact a plurality of bonding pads on the substrate wherein the solder bonding metal layer on the backside of the semiconductor chip strengthens adhesion between the semiconductor chip and the solder film.

19. (Amended) A semiconductor chip package comprising:

a substrate having a plurality of bonding pads;

a semiconductor chip having a plurality of conductive bumps on a front side thereof, the conductive bumps contacting the bonding pads;

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a heat slug bonded to the semiconductor chip, the heat slug comprising a top portion, side standing portions bent from the top portions, and side end portions bent again from the side standing portions; and

a conductive solder film that bonds the heat slug to the backside of the semiconductor chip wherein the heat slug contacts the solder film and the side end portions of the heat slug are attached to the substrate by an adhesive, and wherein the heat slug comprises a solder bonding layer formed on a surface of the heat slug that contacts the solder film.